

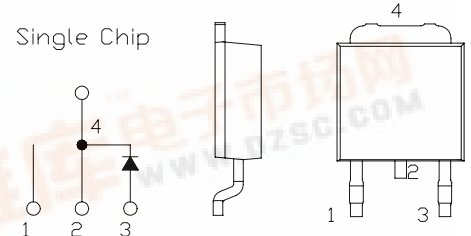


# SBD Type : EA30QS10-F

## OUTLINE DRAWING

### FEATURES

- \* TO-252AA Case, Surface Mounting Device
- \* Low Forward Voltage drop
- \* Low Power Loss
- \* High Surge Capability
- \* 40 Volts thru 100 Volts Types Available
- \* Packaged in 16mm Tape and Reel



### Maximum Ratings

Approx Net Weight:0.30g

Rating	Symbol	EA30QS10-F			Unit
Repetitive Peak Reverse Voltage	$V_{RRM}$	100			V
Average Rectified Output Current	$I_O$	1.6	$T_a=34^{\circ}C$	50Hz Half Sine Wave Resistive Load	A
		3.0	$T_c=133^{\circ}C$		
RMS Forward Current	$I_{F(RMS)}$	4.71			A
Surge Forward Current	$I_{FSM}$	45	50Hz Half Sine Wave, 1cycle, Non-repetitive		A
Operating Junction Temperature Range	$T_{jw}$	- 40 to + 150			$^{\circ}C$
Storage Temperature Range	$T_{stg}$	- 40 to + 150			$^{\circ}C$

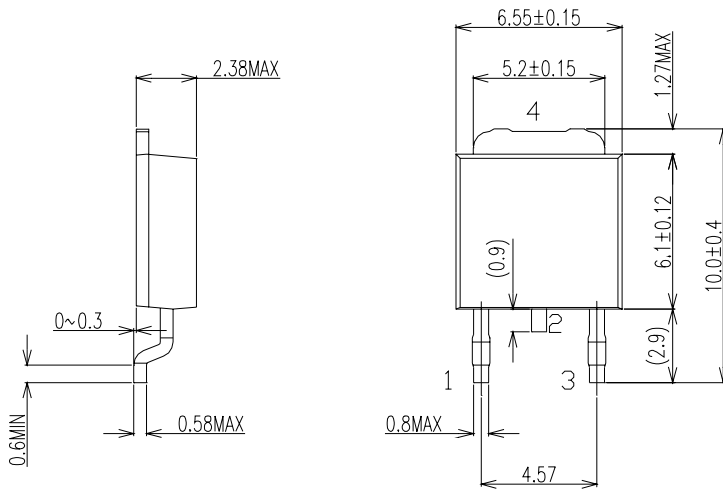
### Electrical • Thermal Characteristics

Characteristics		Symbol	Conditions	Min	Typ	Max	Unit
Peak Reverse Current		$I_{RM}$	$T_j=25^{\circ}C, V_{RM}=V_{RRM}$	-	-	1.0	mA
Peak Forward Voltage		$V_{FM}$	$T_j=25^{\circ}C, I_{FM}= 3 A$	-	-	0.85	V
Thermal Resistance	Junction to Ambient	$R_{th(j-a)}$	P.C.Board mounted *	-	-	80	$^{\circ}C/W$
	Junction to Case	$R_{th(j-c)}$	-	-	-	6	$^{\circ}C/W$

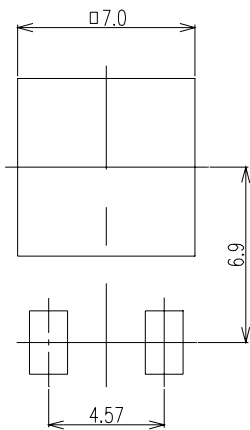
\* Print Land = 20x20 mm



EA30QS10-F OUTLINE DRAWING (Dimensions in mm)



SOLDERING PAD



Single Chip

